

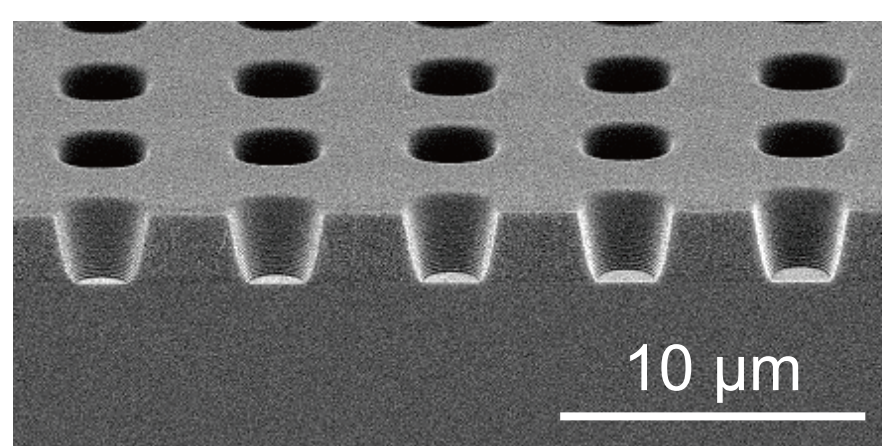
JSR ELPAC™ WPR™ / FG series Photo-Imageable Dielectric (PID)

WPR Series / PFAS Free

Common Features

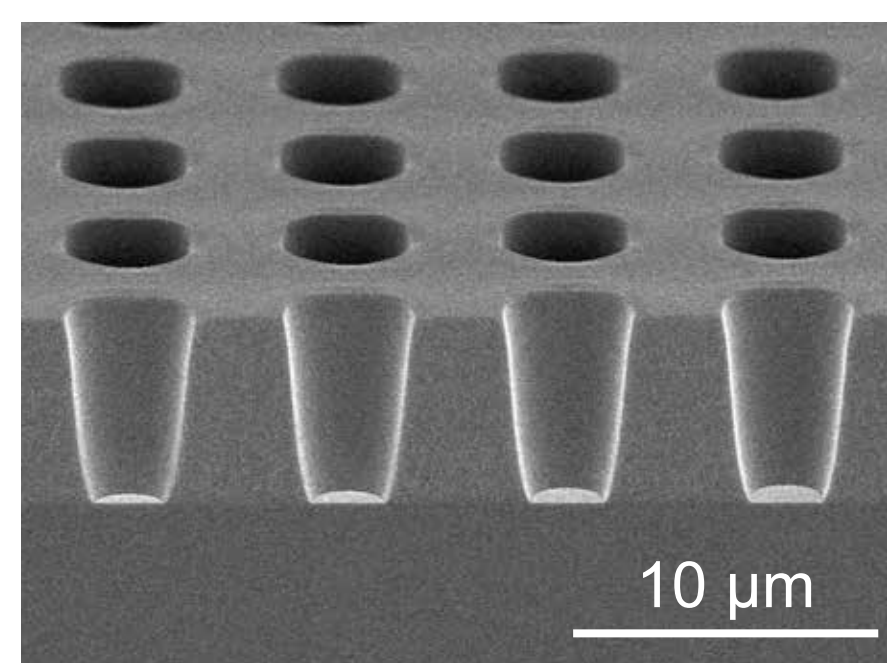
High Resolution
Good adhesion
Low cure temperature

FT = 2~3 μm



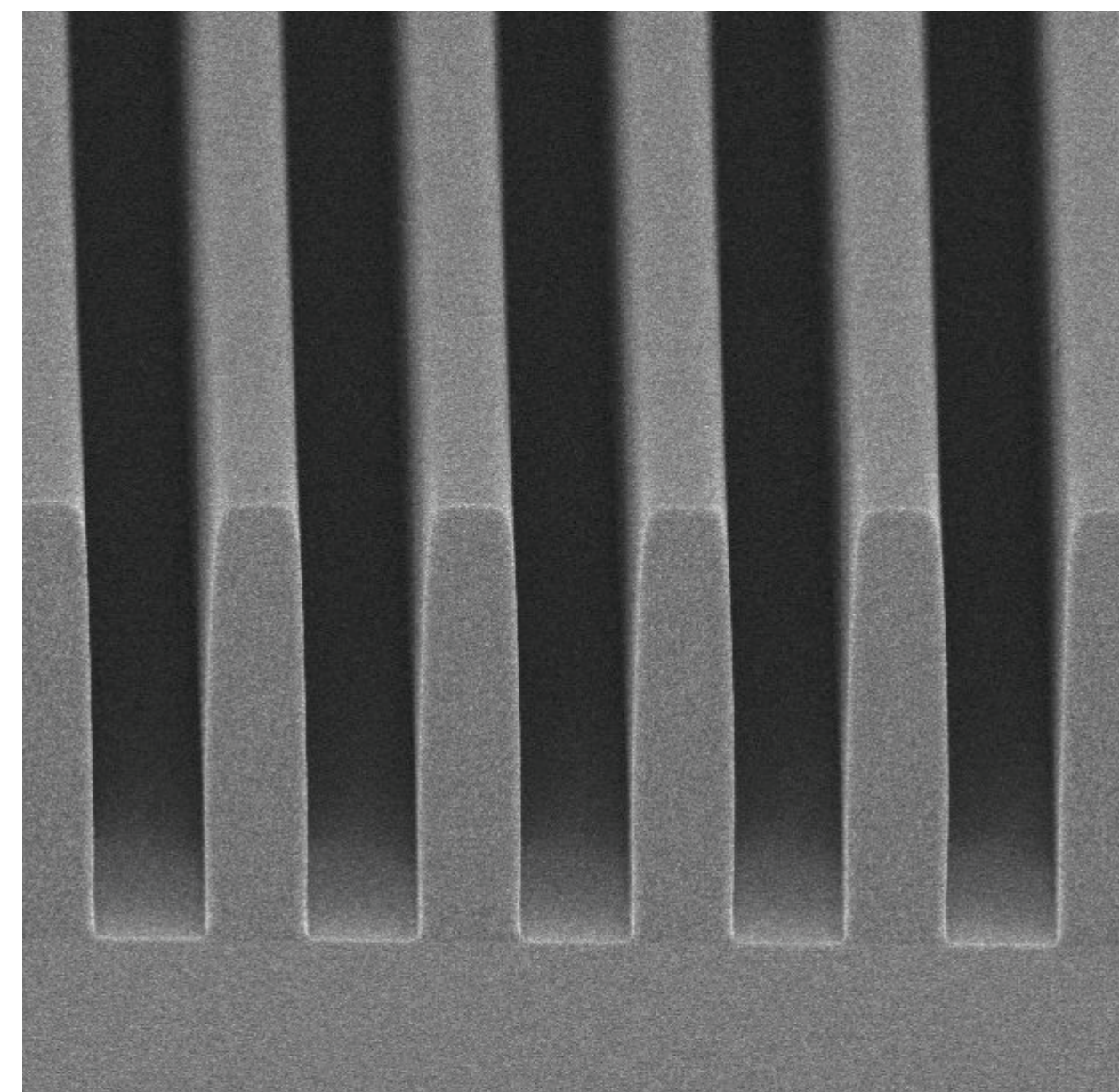
2 μm -SQ

FT = 5~10 μm



2.5 μm -SQ

FT = 10~20 μm



4 μm -L/S

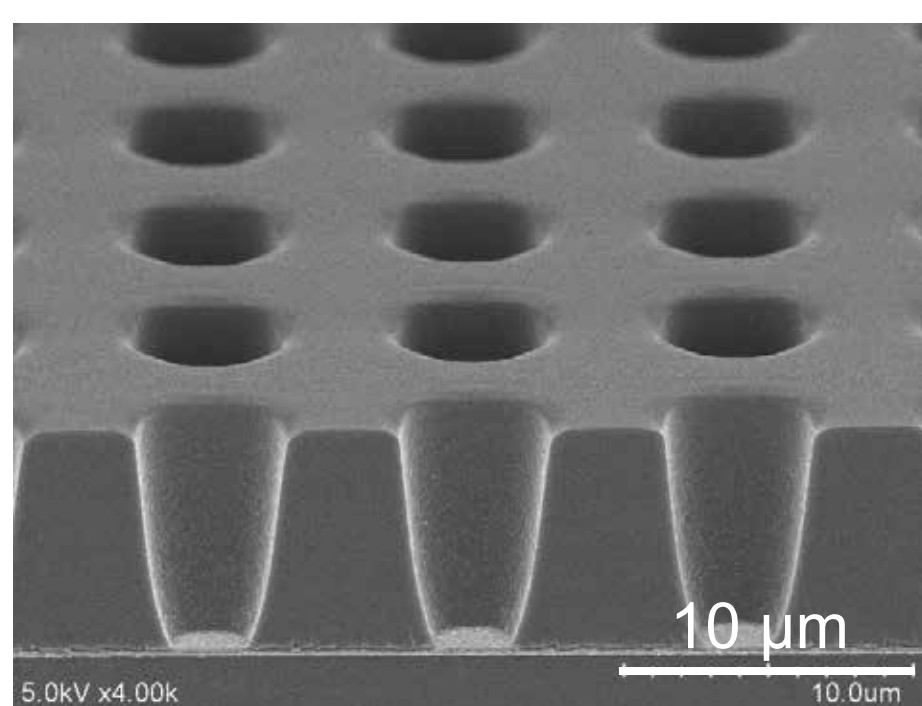
Positive-tone

- ✓ Photo-sensitivity for ghi-line
- ✓ Ideal taper profile

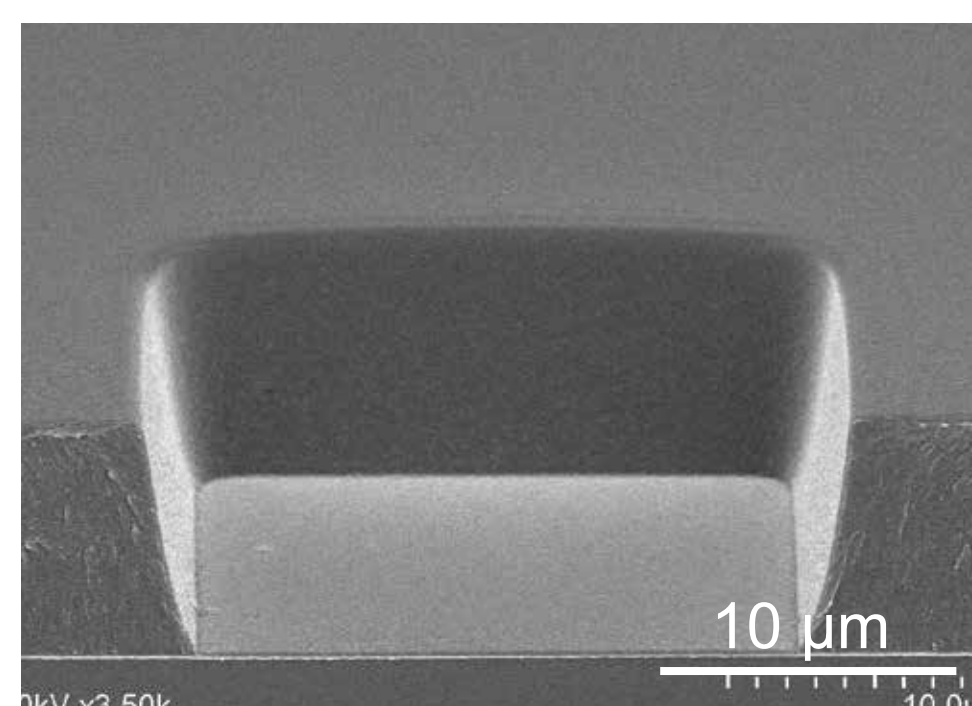
Negative-tone

- ✓ Thick patterning
- ✓ Low warpage

PI Series / PFAS Free Under development



2.5 μm -SQ

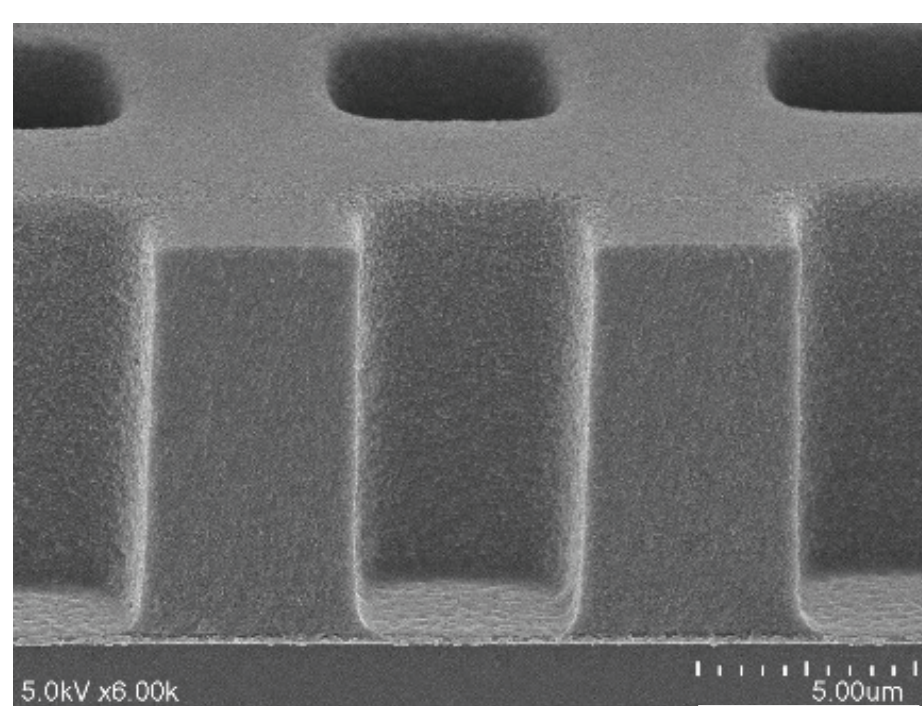


20 μm -SQ

Positive-tone

- ✓ High Resolution
- ✓ Low cure temperature ($\leq 200\text{ }^{\circ}\text{C}$)
- ✓ Good elongation ($>60\%$)
- ✓ High T_g (330 $^{\circ}\text{C}$)

Dry film PID Under development



5 μm -SQ

Negative-tone

- ✓ Dry film for advanced substrate
- ✓ Low CTE (31 ppm/K)
- ✓ Good Cu peel strength (0.4 N/mm)

